

SOLDER PASTE FOR BALL GRID ARRAY

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ABSTRACT OF THE DISCLOSURE

High-quality bumps for a ball grid array can be formed with high yield by the use of solder paste
10 produced by kneading of flux and alloy powders comprising two or more kinds of alloy powders with different compositions, each of the alloy powder having liquidus temperature below reflow temperature, at least one of the alloy powders having a difference of 10°C or more between
15 liquidus and solidus, the average composition of the entire alloy powder being 58 - 65% by weight of tin and 35 - 42% by weight of lead, or 60 - 65% by weight of tin, 34 - 38% by weight of lead, and 1 - 3% by weight of silver.

This Sheet Has Been Replaced

